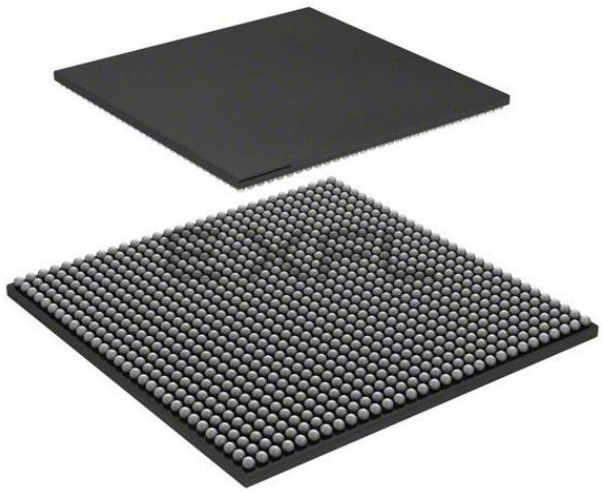

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Understanding Embedded - FPGAs (Field Programmable Gate Array)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details	
Product Status	Obsolete
Number of LABs/CLBs	7776
Number of Logic Elements/Cells	34992
Total RAM Bits	589824
Number of I/O	700
Number of Gates	2188742
Voltage - Supply	1.71V ~ 1.89V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	900-BBGA
Supplier Device Package	900-FBGA (31x31)
Purchase URL	https://www.e-xfl.com/product-detail/xilinx/xcv1600e-8fg900c

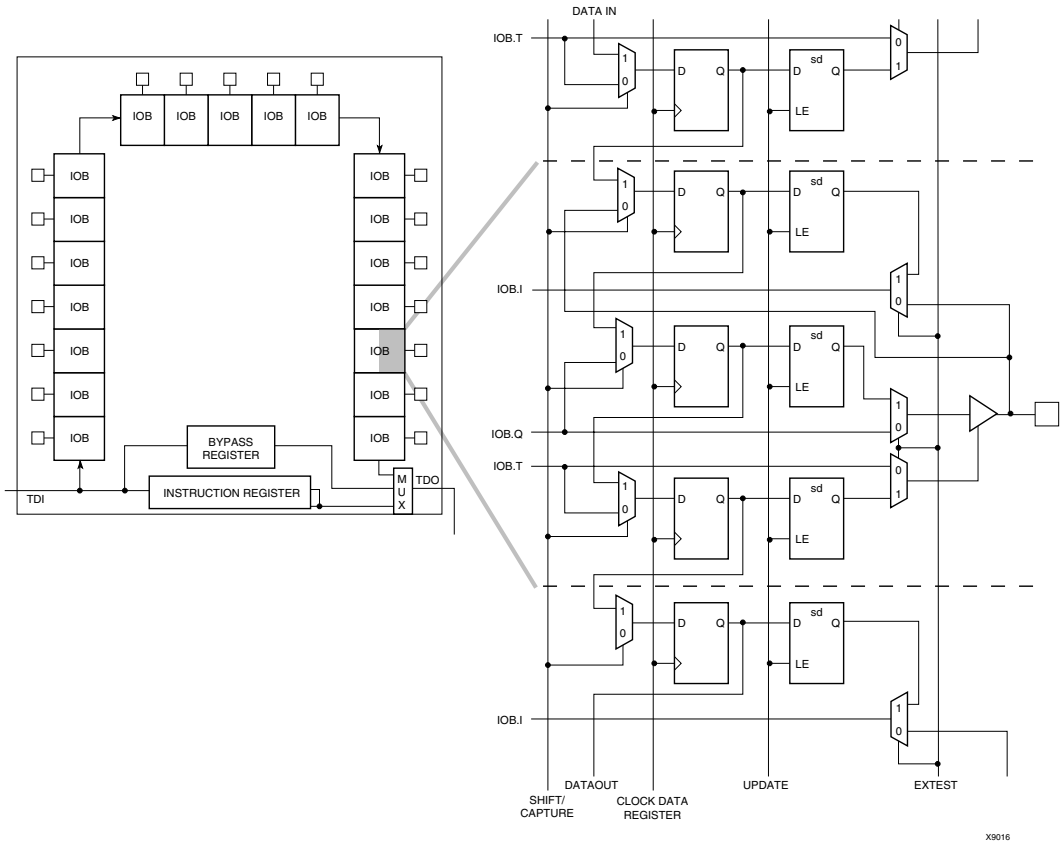

Figure 11: **Virtex-E Family Boundary Scan Logic**

Instruction Set

The Virtex-E series Boundary Scan instruction set also includes instructions to configure the device and read back configuration data (CFG_IN, CFG_OUT, and JSTART). The complete instruction set is coded as shown in Table 6..

Table 6: **Boundary Scan Instructions**

Boundary Scan Command	Binary Code(4:0)	Description
EXTEST	00000	Enables Boundary Scan EXTEST operation
SAMPLE/ PRELOAD	00001	Enables Boundary Scan SAMPLE/PRELOAD operation
USER1	00010	Access user-defined register 1
USER2	00011	Access user-defined register 2
CFG_OUT	00100	Access the configuration bus for read operations.

Table 6: **Boundary Scan Instructions *(Continued)***

Boundary Scan Command	Binary Code(4:0)	Description
CFG_IN	00101	Access the configuration bus for write operations.
INTEST	00111	Enables Boundary Scan INTEST operation
USERCODE	01000	Enables shifting out USER code
IDCODE	01001	Enables shifting out of ID Code
HIGHZ	01010	3-states output pins while enabling the Bypass Register
JSTART	01100	Clock the start-up sequence when StartupClk is TCK
BYPASS	11111	Enables BYPASS
RESERVED	All other codes	Xilinx reserved instructions

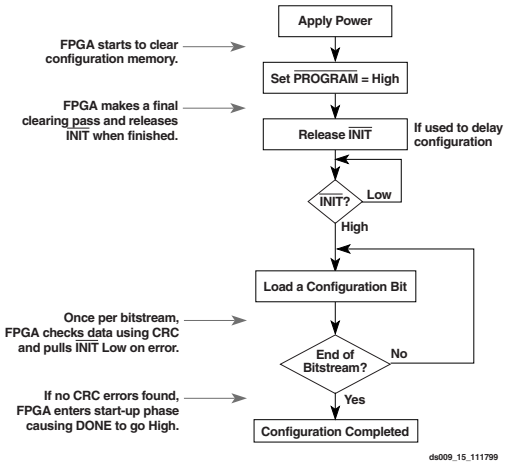

Figure 15: **Serial Configuration Flowchart**

Figure 16 shows the timing of master-serial configuration. Master-serial mode is selected by a <000> or <100> on the mode pins (M2, M1, M0). Table 10 shows the timing information for Figure 16.

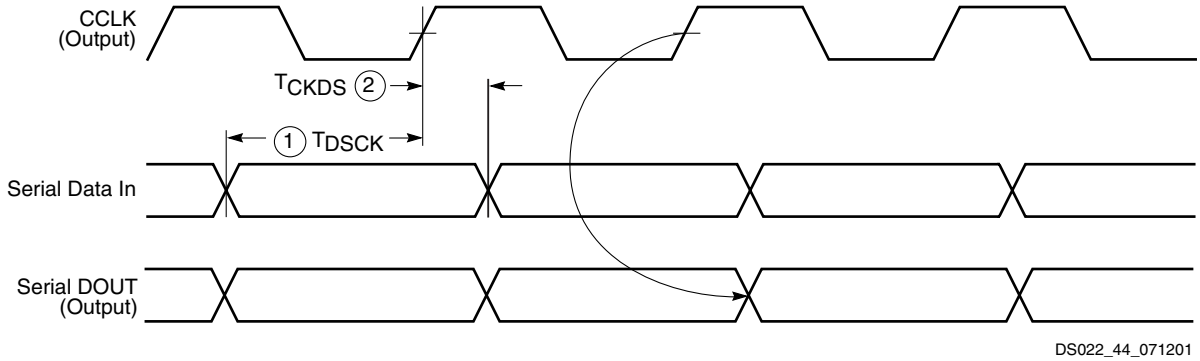

Figure 16: **Master-Serial Mode Programming Switching Characteristics**

At power-up, V_{CC} must rise from 1.0 V to V_{CC} Min in less than 50 ms, otherwise delay configuration by pulling $\overline{\text{PROGRAM}}$ Low until V_{CC} is valid.

SelectMAP Mode

The SelectMAP mode is the fastest configuration option. Byte-wide data is written into the FPGA with a BUSY flag controlling the flow of data.

An external data source provides a byte stream, CCLK, a Chip Select ($\overline{\text{CS}}$) signal and a Write signal ($\overline{\text{WRITE}}$). If BUSY is asserted (High) by the FPGA, the data must be held until BUSY goes Low.

Data can also be read using the SelectMAP mode. If $\overline{\text{WRITE}}$ is not asserted, configuration data is read out of the FPGA as part of a readback operation.

After configuration, the pins of the SelectMAP port can be used as additional user I/O. Alternatively, the port can be retained to permit high-speed 8-bit readback.

Retention of the SelectMAP port is selectable on a design-by-design basis when the bitstream is generated. If retention is selected, PROHIBIT constraints are required to prevent the SelectMAP-port pins from being used as user I/O.

Multiple Virtex-E FPGAs can be configured using the SelectMAP mode, and be made to start-up simultaneously. To configure multiple devices in this way, wire the individual CCLK, Data, $\overline{\text{WRITE}}$, and BUSY pins of all the devices in parallel. The individual devices are loaded separately by asserting the $\overline{\text{CS}}$ pin of each device in turn and writing the appropriate data. See Table 11 for SelectMAP Write Timing Characteristics.

Write

Write operations send packets of configuration data into the FPGA. The sequence of operations for a multi-cycle write operation is shown below. Note that a configuration packet can be split into many such sequences. The packet does not have to complete within one assertion of $\overline{\text{CS}}$, illustrated in Figure 17.

1. Assert $\overline{\text{WRITE}}$ and $\overline{\text{CS}}$ Low. Note that when $\overline{\text{CS}}$ is asserted on successive CCLKs, $\overline{\text{WRITE}}$ must remain either asserted or de-asserted. Otherwise, an abort is initiated, as described below.
2. Drive data onto D[7:0]. Note that to avoid contention, the data source should not be enabled while $\overline{\text{CS}}$ is Low and $\overline{\text{WRITE}}$ is High. Similarly, while $\overline{\text{WRITE}}$ is High, no more that one $\overline{\text{CS}}$ should be asserted.

VHDL Initialization Example

```
library IEEE;
use IEEE.std_logic_1164.all;

entity MYMEM is
port (CLK, WE:in std_logic;
ADDR: in std_logic_vector(8 downto 0);
DIN: in std_logic_vector(7 downto 0);
DOUT: out std_logic_vector(7 downto 0));
end MYMEM;

architecture BEHAVE of MYMEM is
signal logic0, logic1: std_logic;

component RAMB4_S8
--synopsys translate_off
generic( INIT_00,INIT_01, INIT_02, INIT_03, INIT_04, INIT_05, INIT_06, INIT_07,
INIT_08, INIT_09, INIT_0a, INIT_0b, INIT_0c, INIT_0d, INIT_0e, INIT_0f : BIT_VECTOR(255
downto 0)
:= X"0000000000000000000000000000000000000000000000000000000000000000");
--synopsys translate_on
port (WE, EN, RST, CLK: in STD_LOGIC;
ADDR: in STD_LOGIC_VECTOR(8 downto 0);
DI: in STD_LOGIC_VECTOR(7 downto 0);
DO: out STD_LOGIC_VECTOR(7 downto 0));
end component;

--synopsys dc_script_begin
--set_attribute ram0 INIT_00
"0123456789ABCDEF0123456789ABCDEF0123456789ABCDEF0123456789ABCDEF" -type string
--set_attribute ram0 INIT_01
"FEDCBA9876543210FEDCBA9876543210FEDCBA9876543210FEDCBA9876543210" -type string
--synopsys dc_script_end

begin
logic0 <='0';
logic1 <='1';

ram0: RAMB4_S8
--synopsys translate_off
generic map (

INIT_00 => X"0123456789ABCDEF0123456789ABCDEF0123456789ABCDEF0123456789ABCDEF",
INIT_01 => X"FEDCBA9876543210FEDCBA9876543210FEDCBA9876543210FEDCBA9876543210")
--synopsys translate_on
port map (WE=>WE, EN=>logic1, RST=>logic0, CLK=>CLK,ADDR=>ADDR, DI=>DIN, DO=>DOUT);

end BEHAVE;
```

IOB Flip-Flop/Latch Property

The Virtex-E series I/O Block (IOB) includes an optional register on the input path, an optional register on the output path, and an optional register on the 3-state control pin. The design implementation software automatically takes advantage of these registers when the following option for the Map program is specified.

map –pr b <filename>

Alternatively, the IOB = TRUE property can be placed on a register to force the mapper to place the register in an IOB.

Location Constraints

Specify the location of each SelectI/O symbol with the location constraint LOC attached to the SelectI/O symbol. The external port identifier indicates the value of the location constrain. The format of the port identifier depends on the package chosen for the specific design.

The LOC properties use the following form:

LOC=A42

LOC=P37

Output Slew Rate Property

As mentioned above, a variety of symbol names provide the option of choosing the desired slew rate for the output buffers. In the case of the LVTTL output buffers (OBUF, OBUFT, and IOBUF), slew rate control can be alternatively programed with the SLEW= property. By default, the slew rate for each output buffer is reduced to minimize power bus transients when switching non-critical signals. The SLEW= property has one of the two following values.

SLEW=SLOW

SLEW=FAST

Output Drive Strength Property

The desired output drive strength can be additionally specified by choosing the appropriate library symbol. The Xilinx library also provides an alternative method for specifying this feature. For the LVTTL output buffers (OBUF, OBUFT, and IOBUF, the desired drive strength can be specified with the DRIVE= property. This property could have one of the following seven values.

DRIVE=2
DRIVE=4
DRIVE=6
DRIVE=8
DRIVE=12 (Default)
DRIVE=16
DRIVE=24

Design Considerations

Reference Voltage (V_{REF}) Pins

Low-voltage I/O standards with a differential amplifier input buffer require an input reference voltage (V_{REF}). Provide the V_{REF} as an external signal to the device.

The voltage reference signal is “banked” within the device on a half-edge basis such that for all packages there are eight independent V_{REF} banks internally. See Figure 38 for a representation of the Virtex-E I/O banks. Within each bank approximately one of every six I/O pins is automatically configured as a V_{REF} input. After placing a differential amplifier input signal within a given V_{REF} bank, the same external source must drive all I/O pins configured as a V_{REF} input.

Within each V_{REF} bank, any input buffers that require a V_{REF} signal must be of the same type. Output buffers of any type and input buffers can be placed without requiring a reference voltage within the same V_{REF} bank.

Output Drive Source Voltage (V_{CCO}) Pins

Many of the low voltage I/O standards supported by SelectI/O devices require a different output drive source voltage (V_{CCO}). As a result each device can often have to support multiple output drive source voltages.

The Virtex-E series supports eight banks for the HQ and PQ packages. The CS package supports four V_{CCO} banks.

Output buffers within a given V_{CCO} bank must share the same output drive source voltage. Input buffers for LVTTL, LVCMOS2, LVCMOS18, PCI33_3, and PCI 66_3 use the V_{CCO} voltage for Input V_{CCO} voltage.

Transmission Line Effects

The delay of an electrical signal along a wire is dominated by the rise and fall times when the signal travels a short distance. Transmission line delays vary with inductance and capacitance, but a well-designed board can experience delays of approximately 180 ps per inch.

Transmission line effects, or reflections, typically start at 1.5" for fast (1.5 ns) rise and fall times. Poor (or non-existent) termination or changes in the transmission line impedance cause these reflections and can cause additional delay in longer traces. As system speeds continue to increase, the effect of I/O delays can become a limiting factor and therefore transmission line termination becomes increasingly more important.

Termination Techniques

A variety of termination techniques reduce the impact of transmission line effects.

The following are output termination techniques:

- None
- Series
- Parallel (Shunt)
- Series and Parallel (Series-Shunt)

LVTTL

LVTTL requires no termination. DC voltage specifications appears in Table 34.

Table 34: **LVTTL Voltage Specifications**

Parameter	Min	Typ	Max
V_{CCO}	3.0	3.3	3.6
V_{REF}	-	-	-
V_{TT}	-	-	-
V_{IH}	2.0	-	3.6
V_{IL}	–0.5	-	0.8
V_{OH}	2.4	-	-
V_{OL}	-	-	0.4
I_{OH} at V_{OH} (mA)	–24	-	-
I_{OL} at V_{OL} (mA)	24	-	-

Notes:
1. Note: V_{OL} and V_{OH} for lower drive currents sample tested.

LVCMOS2

LVCMOS2 requires no termination. DC voltage specifications appear in Table 35.

Table 35: **LVCMOS2 Voltage Specifications**

Parameter	Min	Typ	Max
V_{CCO}	2.3	2.5	2.7
V_{REF}	-	-	-
V_{TT}	-	-	-
V_{IH}	1.7	-	3.6
V_{IL}	–0.5	-	0.7
V_{OH}	1.9	-	-
V_{OL}	-	-	0.4
I_{OH} at V_{OH} (mA)	–12	-	-
I_{OL} at V_{OL} (mA)	12	-	-

LVCMOS18

LVCMOS18 does not require termination. Table 36 lists DC voltage specifications.

Table 36: **LVCMOS18 Voltage Specifications**

Parameter	Min	Typ	Max
V_{CCO}	1.70	1.80	1.90
V_{REF}	-	-	-
V_{TT}	-	-	-
V_{IH}	0.65 x V_{CCO}	-	1.95
V_{IL}	– 0.5	-	0.2 x V_{CCO}
V_{OH}	V_{CCO} – 0.4	-	-
V_{OL}	-	-	0.4
I_{OH} at V_{OH} (mA)	–8	-	-
I_{OL} at V_{OL} (mA)	8	-	-

AGP-2X

The specification for the AGP-2X standard does not document a recommended termination technique. DC voltage specifications appear in Table 37.

Table 37: **AGP-2X Voltage Specifications**

Parameter	Min	Typ	Max
V_{CCO}	3.0	3.3	3.6
$V_{REF} = N \times V_{CCO}$ (1)	1.17	1.32	1.48
V_{TT}	-	-	-
$V_{IH} = V_{REF} + 0.2$	1.37	1.52	-
$V_{IL} = V_{REF} – 0.2$	-	1.12	1.28
$V_{OH} = 0.9 \times V_{CCO}$	2.7	3.0	-
$V_{OL} = 0.1 \times V_{CCO}$	-	0.33	0.36
I_{OH} at V_{OH} (mA)	Note 2	-	-
I_{OL} at V_{OL} (mA)	Note 2	-	-

Notes:
1. N must be greater than or equal to 0.39 and less than or equal to 0.41.
2. Tested according to the relevant specification.

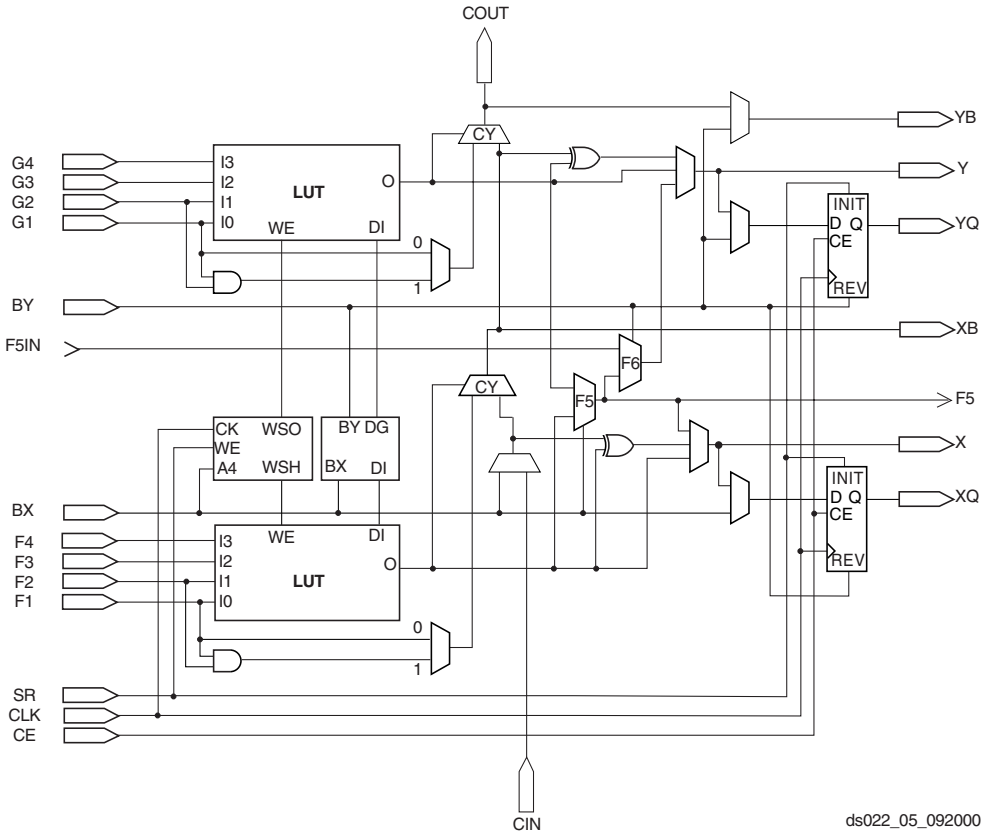

Figure 2: **Detailed View of Virtex-E Slice**

Block RAM Switching Characteristics

Description	Symbol	Speed Grade(1)				Units
		Min	-8	-7	-6	
Sequential Delays						
Clock CLK to DOUT output	T_{BCKO}	0.63	2.46	3.1	3.5	ns, max
Setup and Hold Times before Clock CLK						
ADDR inputs	T_{BACK}/T_{BCKA}	0.42 / 0	0.9 / 0	1.0 / 0	1.1 / 0	ns, min
DIN inputs	T_{BDCK}/T_{BCKD}	0.42 / 0	0.9 / 0	1.0 / 0	1.1 / 0	ns, min
EN input	T_{BECK}/T_{BCKE}	0.97 / 0	2.0 / 0	2.2 / 0	2.5 / 0	ns, min
RST input	T_{BRCK}/T_{BCKR}	0.9 / 0	1.8 / 0	2.1 / 0	2.3 / 0	ns, min
WEN input	T_{BWCK}/T_{BCKW}	0.86 / 0	1.7 / 0	2.0 / 0	2.2 / 0	ns, min
Clock CLK						
Minimum Pulse Width, High	T_{BPWH}	0.6	1.2	1.35	1.5	ns, min
Minimum Pulse Width, Low	T_{BPWL}	0.6	1.2	1.35	1.5	ns, min
CLKA -> CLKB setup time for different ports	T_{BCCS}	1.2	2.4	2.7	3.0	ns, min

Notes:
1. A Zero “0” Hold Time listing indicates no hold time or a negative hold time. Negative values can not be guaranteed “best-case”, but if a “0” is listed, there is no positive hold time.

TBUF Switching Characteristics

Description	Symbol	Speed Grade				Units
		Min	-8	-7	-6	
Combinatorial Delays						
IN input to OUT output	T_{IO}	0.0	0.0	0.0	0 .0	ns, max
TRI input to OUT output high-impedance	T_{OFF}	0.05	0.092	0.10	0.11	ns, max
TRI input to valid data on OUT output	T_{ON}	0.05	0.092	0.10	0.11	ns, max

JTAG Test Access Port Switching Characteristics

Description	Symbol	Value	Units
TMS and TDI Setup times before TCK	T_{TAPTK}	4.0	ns, min
TMS and TDI Hold times after TCK	T_{TCKTAP}	2.0	ns, min
Output delay from clock TCK to output TDO	T_{TCKTDO}	11.0	ns, max
Maximum TCK clock frequency	F_{TCK}	33	MHz, max

Date	Version	Revision
07/23/01	2.2	• Under **Absolute Maximum Ratings**, changed (T_{SOL}) to 220 °C. • Changes made to SSTL symbol names in **IOB Input Switching Characteristics Standard Adjustments** table.
07/26/01	2.3	• Removed T_{SOL} parameter and added footnote to **Absolute Maximum Ratings** table.
9/18/01	2.4	• Reworded power supplies footnote to **Absolute Maximum Ratings** table.
10/25/01	2.5	• Updated the speed grade designations used in data sheets, and added Table 1, which shows the current speed grade designation for each device. • Added XCV2600E and XCV3200E values to **DC Characteristics Over Recommended Operating Conditions** and **Power-On Power Supply Requirements** tables.
11/09/01	2.6	• Updated the **Power-On Power Supply Requirements** table.
02/01/02	2.7	• Updated footnotes to the **DC Input and Output Levels** and **DLL Clock Tolerance, Jitter, and Phase Information** tables.
07/17/02	2.8	• Data sheet designation upgraded from Preliminary to Production. • Removed mention of MIL-M-38510/605 specification. • Added link to XAPP158 from the **Power-On Power Supply Requirements** section.
09/10/02	2.9	• Revised V_{IN} in **Absolute Maximum Ratings** table. • Added Clock CLK switching characteristics to Table **2, "IOB Input Switching Characteristics," on page 6** and **IOB Output Switching Characteristics, Figure 1**.
12/22/02	2.9.1	• Added footnote regarding V_{IN} PCI compliance to **Absolute Maximum Ratings** table. • The fastest ramp rate is 0V to nominal voltage in 2 ms
03/14/03	2.9.2	• Under **Power-On Power Supply Requirements**, the fastest ramp rate is no longer a "suggested" rate.

Virtex-E Data Sheet

The Virtex-E Data Sheet contains the following modules:

- DS022-1, Virtex-E 1.8V FPGAs:
  Introduction and Ordering Information (Module 1)
- DS022-2, Virtex-E 1.8V FPGAs:
  Functional Description (Module 2)
- DS022-3, Virtex-E 1.8V FPGAs:
  DC and Switching Characteristics (Module 3)
- DS022-4, Virtex-E 1.8V FPGAs:
  Pinout Tables (Module 4)

Table 12: **BG432 — XCV300E, XCV400E, XCV600E**

Bank	Pin Description	Pin #
6	VCCO	AL31
7	VCCO	A31
7	VCCO	L28
7	VCCO	L31
NA	GND	A2
NA	GND	A3
NA	GND	A7
NA	GND	A9
NA	GND	A14
NA	GND	A18
NA	GND	A23
NA	GND	A25
NA	GND	A29
NA	GND	A30
NA	GND	B1
NA	GND	B2
NA	GND	B30
NA	GND	B31
NA	GND	C1
NA	GND	C31
NA	GND	D16
NA	GND	G1
NA	GND	G31
NA	GND	J1
NA	GND	J31
NA	GND	P1
NA	GND	P31
NA	GND	T4
NA	GND	T28
NA	GND	V1
NA	GND	V31
NA	GND	AC1
NA	GND	AC31
NA	GND	AE1
NA	GND	AE31

Table 12: **BG432 — XCV300E, XCV400E, XCV600E**

Bank	Pin Description	Pin #
NA	GND	AH16
NA	GND	AJ1
NA	GND	AJ31
NA	GND	AK1
NA	GND	AK2
NA	GND	AK30
NA	GND	AK31
NA	GND	AL2
NA	GND	AL3
NA	GND	AL7
NA	GND	AL9
NA	GND	AL14
NA	GND	AL18
NA	GND	AL23
NA	GND	AL25
NA	GND	AL29
NA	GND	AL30

Notes:

1. V_{REF} or I/O option only in the XCV600E; otherwise, I/O option only.
2. V_{REF} or I/O option only in the XCV400E, XCV600E; otherwise, I/O option only.

Table 17: **FG256 Differential Pin Pair Summary XCV50E, XCV100E, XCV200E, XCV300E**

Pair	Bank	P Pin	N Pin	AO	Other Functions
19	2	C15	D14	√	DIN, D0
20	2	B16	E13	6	VREF
21	2	C16	E14	√	-
22	2	F13	E15	1	VREF
23	2	F12	D16	5	-
24	2	F14	E16	3	D1
25	2	F15	G13	√	D2
26	2	F16	G12	6	-
27	2	G15	G14	√	-
28	2	H13	G16	3	D3
29	2	J13	H15	4	-
30	2	H14	H16	√	-
31	3	K15	J14	4	-
32	3	J16	K16	3	VREF
33	3	K12	L15	√	-
34	3	K13	L16	6	-
35	3	K14	M16	√	D5
36	3	N16	L13	3	VREF
37	3	P16	L12	5	-
38	3	M15	L14	1	VREF
39	3	M14	R16	√	-
40	3	M13	T15	6	VREF
41	3	N14	N15	√	INIT
42	4	T14	P13	√	-
43	4	P12	R13	7	VREF
44	4	N12	T13	√	-
45	4	T12	P11	√	VREF
46	4	R12	N11	2	-
47	4	T11	M11	√	VREF
48	4	R11	T10	√	-
49	4	R10	M10	1	-
50	4	P9	T9	1	VREF
51	4	N10	R9	1	-
52	5	N9	T8	NA	IO_LVDS_DLL
53	5	R7	P8	1	VREF
54	5	P7	T6	1	-

Table 17: **FG256 Differential Pin Pair Summary XCV50E, XCV100E, XCV200E, XCV300E**

Pair	Bank	P Pin	N Pin	AO	Other Functions
55	5	M7	R6	√	-
56	5	P6	R5	√	VREF
57	5	N6	T5	2	-
58	5	M6	T4	√	VREF
59	5	T3	P5	√	-
60	5	T2	N5	7	VREF
61	6	R1	M3	√	-
62	6	N2	M4	6	VREF
63	6	P1	L5	√	-
64	6	L3	N1	1	VREF
65	6	L4	M2	5	-
66	6	K4	M1	3	VREF
67	6	L1	L2	√	-
68	6	K1	K3	6	-
69	6	K5	K2	√	-
70	6	J1	J3	3	VREF
71	6	H1	J4	4	-
72	7	H4	G1	√	-
73	7	H2	G5	4	-
74	7	H3	G4	3	VREF
75	7	F5	G2	√	-
76	7	F1	F4	6	-
77	7	F2	G3	√	-
78	7	D1	E1	3	VREF
79	7	E2	E4	5	-
80	7	C1	F3	1	VREF
81	7	E3	D2	√	-
82	7	A2	B1	6	VREF

Notes:
1. AO in the XCV50E, 200E, 300E.
2. AO in the XCV50E, 200E.
3. AO in the XCV50E, 300E.
4. AO in the XCV100E, 200E.
5. AO in the XCV200E.
6. AO in the XCV100E.
7. AO in the XCV50E.

Table 18: **FG456 — XCV200E and XCV300E**

Bank	Pin Description	Pin #
3	IO_L50N_YY	P19
3	IO_L51P_YY	P18
3	IO_D5_L51N_YY	R21
3	IO_D6_L52P_Y	T22
3	IO_VREF_L52N_Y	R19
3	IO_L53P_Y	U22
3	IO_L53N_Y	R18
3	IO_L54P_YY	T21
3	IO_L54N_YY	V22
3	IO_L55P_YY	T20
3	IO_VREF_L55N_YY	U21
3	IO_L56P_YY	W22
3	IO_L56N_YY	T18
3	IO_L57P_YY	U19
3	IO_VREF_L57N_YY	U20
3	IO_L58P_YY	W21
3	IO_L58N_YY	AA22
3	IO_D7_L59P_YY	Y21
3	IO_INIT_L59N_YY	V19
3	IO	M22
4	GCK0	W12
4	IO	W14
4	IO	Y13
4	IO	Y17
4	IO	AA16[1]
4	IO	AA19
4	IO	AB12[1]
4	IO	AB17
4	IO	AB21[1]
4	IO_L60P_YY	W18
4	IO_L60N_YY	AA20
4	IO_L61P	Y18
4	IO_L61N	V17
4	IO_VREF_L62P_YY	AB20
4	IO_L62N_YY	W17
4	IO_L63P	AA18

Table 18: **FG456 — XCV200E and XCV300E**

Bank	Pin Description	Pin #
4	IO_L63N	V16
4	IO_VREF_L64P_YY	AB19
4	IO_L64N_YY	AB18
4	IO_L65P_Y	W16
4	IO_L65N_Y	AA17
4	IO_L66P_Y	Y16
4	IO_L66N_Y	V15
4	IO_VREF_L67P_YY	AB16
4	IO_L67N_YY	Y15
4	IO_L68P_YY	AA15
4	IO_L68N_YY	AB15
4	IO_L69P_Y	W15
4	IO_L69N_Y	Y14
4	IO_L70P_Y	V14
4	IO_L70N_Y	AA14
4	IO_L71P	AB14
4	IO_L71N	V13
4	IO_VREF_L72P_YY	AA13
4	IO_L72N_YY	AB13
4	IO_L73P_Y	W13
4	IO_L73N_Y	AA12
4	IO_L74P_Y	Y12
4	IO_L74N_Y	V12
4	IO_LVDS_DLL_L75P	U12
5	IO	U11[1]
5	IO	V8
5	IO	W5
5	IO	AA3[1]
5	IO	AA9
5	IO	AA10
5	IO	AB4
5	IO	AB7[1]
5	IO	AB8
5	GCK1	Y11
5	IO_LVDS_DLL_L75N	AA11
5	IO_L76P_Y	AB11

Table 19: **FG456 Differential Pin Pair Summary XCV200E, XCV300E**

Pair	Bank	P Pin	N Pin	AO	Other Functions
88	5	V7	AB3	√	-
89	6	Y2	W3	√	-
90	6	V3	V4	√	-
91	6	U4	Y1	√	VREF
92	6	W1	V2	√	-
93	6	U2	T3	√	VREF
94	6	V1	T5	2	-
95	6	U1	R5	1	-
96	6	T1	R4	2	VREF
97	6	P3	R2	√	-
98	6	R1	P5	√	-
99	6	N5	P2	√	-
100	6	N4	P1	2	-
101	6	N2	N3	1	VREF
102	6	M4	N1	2	-
103	6	M6	M3	√	-
104	7	L4	L3	√	-
105	7	L1	L5	√	-
106	7	K2	L6	2	-
107	7	K3	K4	2	VREF
108	7	K5	K1	√	-
109	7	J2	J3	√	-
110	7	H1	J5	√	-
111	7	H3	H2	√	-
112	7	H4	G1	2	VREF
113	7	F2	F1	2	-
114	7	G3	H5	√	-
115	7	E2	E1	√	VREF
116	7	G5	F3	√	-
117	7	D2	E3	√	VREF
118	7	C1	F5	√	-

Notes:
1. AO in the XCV200E.
2. AO in the XCV300E.

FG676 Fine-Pitch Ball Grid Array Package

XCV400E and XCV600E devices in the FG676 fine-pitch Ball Grid Array package have footprint compatibility. Pins labeled I0_VREF can be used as either in all parts unless device-dependent as indicated in the footnotes. If the pin is not used as V_{REF}, it can be used as general I/O. Immediately following Table 20, see Table 21 for Differential Pair information.

Table 20: **FG676 — XCV400E, XCV600E**

Bank	Pin Description	Pin #
0	GCK3	E13
0	IO	A6
0	IO	A9[1]
0	IO	A10[1]
0	IO	B3
0	IO	B4[1]
0	IO	B12[1]
0	IO	C6
0	IO	C8
0	IO	D5
0	IO	D13[1]
0	IO	G13
0	IO_L0N_Y	C4
0	IO_L0P_Y	F7
0	IO_L1N_YY	G8
0	IO_L1P_YY	C5
0	IO_VREF_L2N_YY	D6
0	IO_L2P_YY	E7
0	IO_L3N	A4
0	IO_L3P	F8
0	IO_L4N	B5
0	IO_L4P	D7
0	IO_VREF_L5N_YY	E8
0	IO_L5P_YY	G9
0	IO_L6N_YY	A5
0	IO_L6P_YY	F9
0	IO_L7N_Y	D8
0	IO_L7P_Y	C7
0	IO_VREF_L8N_Y	B7[2]
0	IO_L8P_Y	E9

Table 22: **FG680 - XCV600E, XCV1000E, XCV1600E, XCV2000E**

Bank	Pin Description	Pin #
6	IO_VREF_L200N_YY	AH39
6	IO_L200P_YY	AG38
6	IO_L201N_YY	AG36
6	IO_L201P_YY	AG39
6	IO_L202N_Y	AG37
6	IO_L202P_Y	AF39
6	IO_L203N	AF36
6	IO_L203P	AE38
6	IO_L204N	AF37
6	IO_L204P	AF38
6	IO_VREF_L205N_Y	AE39[1]
6	IO_L205P_Y	AE36
6	IO_L206N_YY	AD38
6	IO_L206P_YY	AE37
6	IO_L207N	AD39
6	IO_L207P	AD36
6	IO_L208N_Y	AC38
6	IO_L208P_Y	AC39
6	IO_VREF_L209N_YY	AD37
6	IO_L209P_YY	AB38
6	IO_L210N_YY	AC35
6	IO_L210P_YY	AB39
6	IO_L211N	AC36
6	IO_L211P	AA38
6	IO_L212N	AC37
6	IO_L212P	AA39
6	IO_VREF_L213N_YY	AB35
6	IO_L213P_YY	Y38
6	IO_L214N_YY	AB36
6	IO_L214P_YY	Y39
6	IO_VREF_L215N	AB37[2]
6	IO_L215P	AA36
7	IO	C38
7	IO	B37
7	IO	F37

Table 22: **FG680 - XCV600E, XCV1000E, XCV1600E, XCV2000E**

Bank	Pin Description	Pin #
7	IO_L216N_YY	AA37
7	IO_L216P_YY	W38
7	IO_L217N	W37
7	IO_VREF_L217P	V39[2]
7	IO_L218N_YY	W36
7	IO_L218P_YY	U39
7	IO_L219N_YY	V38
7	IO_VREF_L219P_YY	U38
7	IO_L220N	V37
7	IO_L220P	T39
7	IO_L221N	V36
7	IO_L221P	T38
7	IO_L222N_YY	V35
7	IO_L222P_YY	R39
7	IO_L223N_YY	U37
7	IO_VREF_L223P_YY	U36
7	IO_L224N_Y	R38
7	IO_L224P_Y	U35
7	IO_L225N	P39
7	IO_L225P	T37
7	IO_L226N_YY	P38
7	IO_L226P_YY	T36
7	IO_L227N_Y	N39
7	IO_VREF_L227P_Y	N38[1]
7	IO_L228N	R37
7	IO_L228P	M39
7	IO_L229N	R36
7	IO_L229P	M38
7	IO_L230N_Y	P37
7	IO_L230P_Y	L39
7	IO_L231N_YY	P36
7	IO_L231P_YY	N37
7	IO_L232N_YY	L38
7	IO_VREF_L232P_YY	N36
7	IO_L233N	K39
7	IO_L233P	M37

Table 24: **FG860 — XCV1000E, XCV1600E, XCV2000E**

Bank	Pin Description	Pin #
0	IO_VREF_L27N_YY	D27
0	IO_L27P_YY	B25
0	IO_L28N_Y	A25
0	IO_L28P_Y	D26
0	IO_L29N_Y	A24
0	IO_L29P_Y	E25
0	IO_L30N_YY	D25
0	IO_L30P_YY	B24
0	IO_VREF_L31N_YY	E24
0	IO_L31P_YY	A23
0	IO_L32N_Y	C23
0	IO_L32P_Y	E23
0	IO_VREF_L33N_Y	B23[1]
0	IO_L33P_Y	D23
0	IO_LVDS_DLL_L34N	A22
1	GCK2	B22
1	IO	A14
1	IO	A20
1	IO	B11
1	IO	B13
1	IO	C8
1	IO	C18
1	IO	C21
1	IO	D7
1	IO	D10
1	IO	D15
1	IO	D17
1	IO	E20
1	IO_LVDS_DLL_L34P	D22
1	IO_L35N_Y	D21
1	IO_VREF_L35P_Y	B21[1]
1	IO_L36N_Y	D20
1	IO_L36P_Y	A21
1	IO_L37N_YY	C20
1	IO_VREF_L37P_YY	D19
1	IO_L38N_YY	B20

Table 24: **FG860 — XCV1000E, XCV1600E, XCV2000E**

Bank	Pin Description	Pin #
1	IO_L38P_YY	E19
1	IO_L39N_Y	D18
1	IO_L39P_Y	A19
1	IO_L40N_Y	E18
1	IO_L40P_Y	C19
1	IO_L41N_YY	B19
1	IO_VREF_L41P_YY	E17
1	IO_L42N_YY	A18
1	IO_L42P_YY	D16
1	IO_L43N_Y	E16
1	IO_L43P_Y	B18
1	IO_L44N_Y	F16
1	IO_L44P_Y	A17
1	IO_L45N_YY	C17
1	IO_VREF_L45P_YY	E15
1	IO_L46N_YY	B17
1	IO_L46P_YY	D14
1	IO_L47N_Y	A16
1	IO_L47P_Y	E14
1	IO_L48N_Y	C16
1	IO_L48P_Y	D13
1	IO_L49N_Y	B16
1	IO_L49P_Y	D12
1	IO_L50N_Y	A15
1	IO_L50P_Y	E12
1	IO_L51N_YY	C15
1	IO_L51P_YY	C11
1	IO_L52N_YY	B15
1	IO_VREF_L52P_YY	D11
1	IO_L53N_Y	E11
1	IO_L53P_Y	C14
1	IO_L54N_Y	C10
1	IO_L54P_Y	B14
1	IO_L55N_YY	A13
1	IO_VREF_L55P_YY	E10
1	IO_L56N_YY	C13
1	IO_L56P_YY	C9

Table 24: **FG860 — XCV1000E, XCV1600E, XCV2000E**

Bank	Pin Description	Pin #
NA	VCCO_1	F15
NA	VCCO_1	F19
NA	VCCO_1	F20
NA	VCCO_1	F7
NA	VCCO_1	F8
NA	VCCO_2	G6
NA	VCCO_2	H6
NA	VCCO_2	L6
NA	VCCO_2	M6
NA	VCCO_2	P6
NA	VCCO_2	R6
NA	VCCO_2	W6
NA	VCCO_2	Y6
NA	VCCO_3	AC6
NA	VCCO_3	AD6
NA	VCCO_3	AH6
NA	VCCO_3	AJ6
NA	VCCO_3	AL6
NA	VCCO_3	AM6
NA	VCCO_3	AR6
NA	VCCO_3	AT6
NA	VCCO_4	AU11
NA	VCCO_4	AU12
NA	VCCO_4	AU14
NA	VCCO_4	AU15
NA	VCCO_4	AU19
NA	VCCO_4	AU20
NA	VCCO_4	AU7
NA	VCCO_4	AU8
NA	VCCO_5	AU23
NA	VCCO_5	AU24
NA	VCCO_5	AU28
NA	VCCO_5	AU29
NA	VCCO_5	AU31
NA	VCCO_5	AU32
NA	VCCO_5	AU35
NA	VCCO_5	AU36

Table 24: **FG860 — XCV1000E, XCV1600E, XCV2000E**

Bank	Pin Description	Pin #
NA	VCCO_6	AC37
NA	VCCO_6	AD37
NA	VCCO_6	AH37
NA	VCCO_6	AJ37
NA	VCCO_6	AL37
NA	VCCO_6	AM37
NA	VCCO_6	AR37
NA	VCCO_6	AT37
NA	VCCO_7	G37
NA	VCCO_7	H37
NA	VCCO_7	L37
NA	VCCO_7	M37
NA	VCCO_7	P37
NA	VCCO_7	R37
NA	VCCO_7	W37
NA	VCCO_7	Y37
NA	GND	N6
NA	GND	N5
NA	GND	N38
NA	GND	N37
NA	GND	F6
NA	GND	F37
NA	GND	F30
NA	GND	F22
NA	GND	F21
NA	GND	F13
NA	GND	E5
NA	GND	E38
NA	GND	E30
NA	GND	E22
NA	GND	E21
NA	GND	E13
NA	GND	D42
NA	GND	D4
NA	GND	D39
NA	GND	D1

Table 26: **FG900 — XCV600E, XCV1000E, XCV1600E**

Bank	Pin Description	Pin #
3	IO_L127P_YY	Y24
3	IO_VREF_L127N_YY	AB28
3	IO_L128P_YY	AC30
3	IO_L128N_YY	AA25
3	IO_L129P	W21
3	IO_L129N	AA24
3	IO_L130P_YY	AB26
3	IO_L130N_YY	AD30
3	IO_L131P_YY	Y22
3	IO_VREF_L131N_YY	AC27
3	IO_L132P	AD28
3	IO_L132N	AB25
3	IO_L133P_YY	AC26
3	IO_L133N_YY	AE30
3	IO_L134P_YY	AD27
3	IO_L134N_YY	AF30
3	IO_L135P	AF29
3	IO_VREF_L135N	AB24
3	IO_L136P_YY	AB23
3	IO_L136N_YY	AE28
3	IO_L137P_Y	AG30[3]
3	IO_L137N_Y	AC25[4]
3	IO_L138P_YY	AE26
3	IO_VREF_L138N_YY	AG29[1]
3	IO_L139P	AH30
3	IO_L139N	AC24
3	IO_L140P	AF28[3]
3	IO_L140N	AD25[4]
3	IO_D7_L141P_YY	AH29
3	IO_INIT_L141N_YY	AA22
4	GCK0	AJ16
4	IO	AB19[4]
4	IO	AC16[4]
4	IO	AC19
4	IO	AD18[4]
4	IO	AD21[4]

Table 26: **FG900 — XCV600E, XCV1000E, XCV1600E**

Bank	Pin Description	Pin #
4	IO	AE15[4]
4	IO	AE18[4]
4	IO	AE21
4	IO	AE24[5]
4	IO	AF17[5]
4	IO	AF18[5]
4	IO	AJ18[4]
4	IO	AK18
4	IO	AK25[5]
4	IO	AK27[4]
4	IO	AH23[4]
4	IO	AH24[5]
4	IO_L142P_YY	AF27
4	IO_L142N_YY	AK28
4	IO_L143P_YY	AG26[4]
4	IO_L143N_YY	AH27[3]
4	IO_L144P	AD23
4	IO_L144N	AJ27
4	IO_VREF_L145P	AB21[1]
4	IO_L145N	AF25
4	IO_L146P	AC22[4]
4	IO_L146N	AH26[4]
4	IO_L147P_YY	AA21
4	IO_L147N_YY	AG25
4	IO_VREF_L148P_YY	AJ26
4	IO_L148N_YY	AD22
4	IO_L149P	AA20
4	IO_L149N	AH25
4	IO_L150P	AC21
4	IO_L150N	AF24
4	IO_L151P_YY	AG24
4	IO_L151N_YY	AK26
4	IO_VREF_L152P_YY	AJ24
4	IO_L152N_YY	AF23
4	IO_L153P	AE23
4	IO_L153N	AB20
4	IO_L154P	AC20

Table 26: **FG900 — XCV600E, XCV1000E, XCV1600E**

Bank	Pin Description	Pin #
NA	GND	AG27
NA	GND	D27
NA	GND	AF26
NA	GND	E26
NA	GND	F25
NA	GND	AE25
NA	GND	G24
NA	GND	AJ23
NA	GND	AD24
NA	GND	H23
NA	GND	B23
NA	GND	AC23
NA	GND	AB22
NA	GND	V22
NA	GND	N22
NA	GND	AH18
NA	GND	AB18
NA	GND	J18
NA	GND	C18
NA	GND	U17
NA	GND	T17
NA	GND	R17
NA	GND	P17
NA	GND	U16
NA	GND	T16
NA	GND	R16
NA	GND	P16
NA	GND	U15
NA	GND	T15
NA	GND	R15
NA	GND	P15
NA	GND	U14
NA	GND	T14
NA	GND	R14
NA	GND	P14
NA	GND	AH13
NA	GND	AB13

Table 26: **FG900 — XCV600E, XCV1000E, XCV1600E**

Bank	Pin Description	Pin #
NA	GND	J13
NA	GND	C13
NA	GND	V9
NA	GND	N9
NA	GND	J9
NA	GND	AJ8
NA	GND	AC8
NA	GND	H8
NA	GND	AD7
NA	GND	B8
NA	GND	AE6
NA	GND	G7
NA	GND	F6
NA	GND	AF5
NA	GND	E5
NA	GND	AG4
NA	GND	D4
NA	GND	V3
NA	GND	N3
NA	GND	C3
NA	GND	AK2
NA	GND	AH3
NA	GND	AC2
NA	GND	H2
NA	GND	B2
NA	GND	A2
NA	GND	AK1
NA	GND	AJ2
NA	GND	AJ1
NA	GND	A1
NA	GND	B1

Notes:

1. V_{REF} or I/O option only in the XCV1000E and XCV1600E; otherwise, I/O option only.
2. V_{REF} or I/O option only in the XCV1600E; otherwise, I/O option only.
3. I/O option only in the XCV600E.
4. No Connect in the XCV600E.
5. No Connect in the XCV600E, 1000E.

Table 28: **FG1156 — XCV1000E, XCV1600E, XCV2000E, XCV2600E, XCV3200E**

Bank	Pin Description	Pin #
0	IO_L6P_YY	H10[5]
0	IO_L7N_Y	D7
0	IO_L7P_Y	B5
0	IO_L8N_Y	K12
0	IO_L8P_Y	E8
0	IO_L9N	B6[4]
0	IO_L9P	F9[5]
0	IO_L10N_YY	G10
0	IO_L10P_YY	C7
0	IO_VREF_L11N_YY	D8
0	IO_L11P_YY	B7
0	IO_L12N	H11[4]
0	IO_L12P	C8[5]
0	IO_L13N_Y	E9
0	IO_L13P_Y	B8
0	IO_VREF_L14N_Y	K13[2]
0	IO_L14P_Y	G11
0	IO_L15N	A8[4]
0	IO_L15P	F10[5]
0	IO_L16N_YY	C9
0	IO_L16P_YY	H12
0	IO_VREF_L17N_YY	D10
0	IO_L17P_YY	A9
0	IO_L18N_Y	F11
0	IO_L18P_Y	A10
0	IO_L19N_Y	K14
0	IO_L19P_Y	C10
0	IO_VREF_L20N_YY	H13
0	IO_L20P_YY	G12
0	IO_L21N_YY	A11
0	IO_L21P_YY	B11
0	IO_L22N_Y	E12
0	IO_L22P_Y	D11
0	IO_L23N_Y	G13

Table 28: **FG1156 — XCV1000E, XCV1600E, XCV2000E, XCV2600E, XCV3200E**

Bank	Pin Description	Pin #
0	IO_L23P_Y	C12
0	IO_L24N_Y	K15
0	IO_L24P_Y	A12
0	IO_L25N_Y	B12
0	IO_L25P_Y	H14
0	IO_L26N_YY	D12
0	IO_L26P_YY	F13
0	IO_VREF_L27N_YY	A13
0	IO_L27P_YY	B13
0	IO_L28N_YY	J15[4]
0	IO_L28P_YY	G14[5]
0	IO_L29N_Y	C13
0	IO_L29P_Y	F14
0	IO_L30N_Y	H15
0	IO_L30P_Y	D13
0	IO_L31N	A14[4]
0	IO_L31P	K16[5]
0	IO_L32N_YY	E14
0	IO_L32P_YY	B14
0	IO_VREF_L33N_YY	G15
0	IO_L33P_YY	D14
0	IO_L34N	J16[4]
0	IO_L34P	D15[5]
0	IO_L35N_Y	F15
0	IO_L35P_Y	B15
0	IO_L36N_Y	A15
0	IO_L36P_Y	E15
0	IO_L37N	G16[4]
0	IO_L37P	A16[5]
0	IO_L38N_YY	F16
0	IO_L38P_YY	J17
0	IO_VREF_L39N_YY	C16
0	IO_L39P_YY	B16
0	IO_L40N_Y	H17

Table 28: **FG1156 — XCV1000E, XCV1600E, XCV2000E, XCV2600E, XCV3200E**

Bank	Pin Description	Pin #
2	IO_L126N_YY	T32
2	IO_VREF_L127P_Y	U29[1]
2	IO_L127N_Y	U33
2	IO_L128P_YY	V33
2	IO_L128N_YY	U31
3	IO	V27[3]
3	IO	V31
3	IO	V32[3]
3	IO	W33
3	IO	AB25[3]
3	IO	AB26[3]
3	IO	AB31[3]
3	IO	AC31[3]
3	IO	AF34
3	IO	AG31[3]
3	IO	AG33[3]
3	IO	AG34
3	IO	AH29[3]
3	IO	AJ30[3]
3	IO_L129P_Y	V26
3	IO_VREF_L129N_Y	V30[1]
3	IO_L130P_YY	W34
3	IO_L130N_YY	V28
3	IO_L131P_YY	W32
3	IO_VREF_L131N_YY	W30
3	IO_L132P_Y	V29
3	IO_L132N_Y	Y34
3	IO_L133P	W29[5]
3	IO_L133N	Y33[4]
3	IO_L134P_Y	W26
3	IO_L134N_Y	W28
3	IO_L135P_YY	Y31
3	IO_L135N_YY	Y30

Table 28: **FG1156 — XCV1000E, XCV1600E, XCV2000E, XCV2600E, XCV3200E**

Bank	Pin Description	Pin #
3	IO_L136P_YY	AA34[5]
3	IO_L136N_YY	W31[4]
3	IO_D4_L137P_YY	AA33
3	IO_VREF_L137N_YY	Y29
3	IO_L138P_Y	W25
3	IO_L138N_Y	AB34
3	IO_L139P_Y	Y28[5]
3	IO_L139N_Y	AB33[4]
3	IO_L140P_Y	AA30
3	IO_L140N_Y	Y26
3	IO_L141P_YY	Y27
3	IO_L141N_YY	AA31
3	IO_L142P_YY	AA27[5]
3	IO_L142N_YY	AA29[4]
3	IO_L143P_Y	AB32
3	IO_VREF_L143N_Y	AB29
3	IO_L144P_Y	AA28
3	IO_L144N_Y	AC34
3	IO_L145P	Y25
3	IO_L145N	AD34
3	IO_L146P_Y	AB30
3	IO_L146N_Y	AC33
3	IO_L147P_Y	AA26
3	IO_L147N_Y	AC32
3	IO_L148P_Y	AD33
3	IO_L148N_Y	AB28
3	IO_L149P_YY	AE34
3	IO_D5_L149N_YY	AB27
3	IO_D6_L150P_YY	AE33
3	IO_VREF_L150N_YY	AC30
3	IO_L151P_Y	AA25
3	IO_L151N_Y	AE32
3	IO_L152P_YY	AE31
3	IO_L152N_YY	AD29

Table 29: **FG1156 Differential Pin Pair Summary: XCV1000E, XCV1600E, XCV2000E, XCV2600E, XCV3200E**

Pair	Bank	P Pin	N Pin	AO	Other Functions
32	0	B14	E14	3200 2600 2000 1600 1000	-
33	0	D14	G15	3200 2600 2000 1600 1000	VREF
34	0	D15	J16	3200 1600	-
35	0	B15	F15	3200 2000 1000	-
36	0	E15	A15	3200 2000 1000	-
37	0	A16	G16	3200 2600	-
38	0	J17	F16	3200 2600 2000 1600 1000	-
39	0	B16	C16	3200 2600 2000 1600 1000	VREF
40	0	A17	H17	2600 1600 1000	-
41	0	B17	G17	2600 1600 1000	VREF
42	1	J18	C17	None	IO_LVDS_DLL
43	1	C18	G18	2600 1600 1000	VREF
44	1	F18	H18	2600 1600 1000	-
45	1	A19	B19	3200 2600 2000 1600 1000	VREF
46	1	C19	K19	3200 2600 2000 1600 1000	-
47	1	E19	F19	3200 2600	-
48	1	J19	G19	3200 2000 1000	-
49	1	G20	A20	3200 2000 1000	-
50	1	F20	B20	3200 1600	-
51	1	E20	D20	3200 2600 2000 1600 1000	VREF

Table 29: **FG1156 Differential Pin Pair Summary: XCV1000E, XCV1600E, XCV2000E, XCV2600E, XCV3200E**

Pair	Bank	P Pin	N Pin	AO	Other Functions
52	1	A21	H20	3200 2600 2000 1600 1000	-
53	1	J20	E21	3200	-
54	1	K20	D21	3200 2600 1000	-
55	1	H21	B21	3200 2600 1000	-
56	1	F21	G21	2000 1600	-
57	1	B22	A22	3200 2600 2000 1600 1000	VREF
58	1	C22	J21	3200 2600 2000 1600 1000	-
59	1	G22	D22	3200 2600 1000	-
60	1	A23	K21	3200 2000 1000	-
61	1	B23	F22	3200 2000 1000	-
62	1	H22	C23	3200 1600 1000	-
63	1	K22	D23	3200 2600 2000 1600 1000	-
64	1	J22	A24	3200 2600 2000 1600 1000	VREF
65	1	D24	H23	2600 1600 1000	-
66	1	E24	A25	2600 1600 1000	-
67	1	C25	A26	3200 2600 2000 1600 1000	VREF
68	1	B26	F24	3200 2600 2000 1600 1000	-
69	1	F25	K23	3200 2600	-
70	1	H24	C26	3200 2000 1000	VREF